10 December 1968

TEST PLAN
[redacted] PROCESSOR

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REFERENCE: Contract [redacted] dated 30 June 1965 [redacted]

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1. INTRODUCTION

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1.1. The development of the [redacted] Air Bearing Wide Film Processor was initiated by contract [redacted] in June 1965. After completion of the design-study-breadboard phase which established the working parameters for a prototype model, phase II prototype manufacture commenced in late 1966. After an in-plant checkout of the processor by NPIC personnel in June 1967, it was delivered [redacted] for a thorough test and evaluation prior to installation at NPIC. The processor subsequently failed to pass acceptance testing and was shipped back to the contractor in November 1967. The contractor for several months was reluctant to correct the deficiencies found [redacted] however, in July 1968 the contractor agreed to re-work the equipment.

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1.2. This test plan describes in general terms a test and evaluation program which TSSG/ESD/TEB proposes to accomplish. This program will be accomplished in four phases unless it is terminated because the results of any test and evaluation phase indicate a total rejection of the equipment. It is expected that the processor will be ready for pre-acceptance (phase I) in early February 1969 with delivery of the unit to NPIC in late February 1969.

2. PRE-ACCEPTANCE TEST (PHASE I)

2.1. Pre-acceptance tests will be performed by the contractor at his plant and witnessed by the TSSG/DED contract monitor, a representative of PSG/RD/PSB, and the test engineer from TSSG/ESD/TEB. Additional tests might be suggested by the ESD/TEB test engineer who will assist the DED contract monitor in making the technical evaluation of all test results.

2.2. It will be determined in this phase if the equipment is operative and if any glaring contract discrepancies exist. Equipment will be checked for compliance with section 2 of the contractor's technical proposal number 25X1 [redacted] an integral part of the reference contract. Particular emphasis will be placed upon corrections made for discrepancies outlined to the contractor when the equipment was rejected and returned for re-work. It is estimated that three to five days at the contractor's plant will be required to perform pre-acceptance tests.

2.3. The ESD/TEB test engineer will make recommendations as to pre-acceptance, however, primary responsibility for preliminary acceptance and agreement for shipping the processor belongs to the DED contract monitor.

3. ACCEPTANCE TESTS (PHASE II)

25X1 3.1. Upon arrival at NPIC, the [redacted] Processor will be installed in the photo lab area of PSG/RD/PSB where phase II, III and IV tests will be conducted. Acceptance tests will be conducted by the ESD/TEB test engineer.

3.2. The purpose of this phase is to provide minute inspection and detailed testing of the equipment to determine if the manufacturer has met minimum contract specifications (contractor's technical proposal number 25X1 [redacted]

3.3. It is estimated that this phase will require from one to two months time. Information on any contract specification discrepancies found will be forwarded to the DED contract monitor at the earliest time possible. Sufficient data to justify a waiver to contract specification discrepancies or to establish why a waiver should not be granted will be provided the contract monitor if requested.

3.4. The results of this acceptance test phase will be made available to TSSG/DED in a timely written interim report. It is intended that this report will provide guidance for deciding appropriate final contractual action.

4. ENGINEERING TEST (PHASE III)

25X1 4.1. The [redacted] Processor will remain in the same location as for phase II testing. It will be subjected to a testing procedure to determine its maximum performance capability. This test phase is for:

1. Providing data for possible follow-on development of the prototype equipment. This will include data on poor design areas along with suggested improvements.

2. Establishing a confidence level for the reliability and product quality which the equipment can produce.

3. Establishing if equipment will meet the operational requirements of PSG/RD/PSB (Note: If requirements are not given to test engineer it will be assumed that they are the same as those inferred by the contractor's technical proposal.)

None.

4.2. It is estimated that this phase will require from two to three months time, but will start at the same time as phase II and will run concurrently with that phase.

5. OPERATIONAL SUITABILITY TESTS (PHASE IV)

5.1. Phase IV will be conducted only if phase III test results indicate that the equipment is engineered to an acceptable level for operational use. This phase will be conducted jointly between the user (PSG/RD/PSB) and the test engineer of TSSG/ESD/TEB. The processor will remain in the same location as for test phases II and III.

5.2. The purpose of this phase is to determine the operational capabilities and limitations of the equipment in terms of operational tactics, techniques and standards. The duration of this testing phase will be determined jointly at that time.

6. TEST AND EVALUATION REPORT

Upon completion of the testing program described herein, an overall test and evaluation report will be produced. This final report will contain details of all testing performed and will contain conclusions and recommendations. It is planned to distribute this report to all operating components within NPIC, to EXRAND committee members and to other qualified components upon request. If the program is terminated because of a final rejection of equipment in phase II or III, a report as described will still be produced.

7. ASSISTANCE REQUIRED

7.1. Assistance will be required from the TSSG/DED contract monitor for providing:

1) An insight to the contractor's engineering problems in designing the prototype equipment.

2) Data as to requirements for the equipment.

3) Any liaison required between the contractor and the test engineer on specific problems requiring contractor's assistance.

7.2. Assistance will be required from PSG/RD/PSB to:

1) Provide a film processing darkroom in the photo lab area for 25X1 installation of the [redacted] Processor for all test phases conducted at 25X1 NPIC. Minimum size room required is 18 by 10 feet. This room should be one where room lights can be turned on at any time without hindering other work progress. Doors to this room must be wide enough to accept the [redacted] which is approximately 42 inches wide. Electric power, chemical drain and pipe line connections to chemical tank farm will be required.

2) Various film materials and widths will be required for use in test- 25X1 ing the [redacted] Processor. It is expected that small quantities of this material will be supplied from normal PSG/RD/PSB inventory. Assistance may be requested in procuring additional quantities where supply is limited and/or types of films are not normally stocked:

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3) Chemical tank farm support. If proprietary chemistry or additional chemicals for mixing standard processing formulas are required, assistance may be requested for procuring these chemicals.

4) Provide printing services to supply ample test roll exposures for 25X1 processing in the [redacted] Processor. (Note: An estimate of film materials and chemicals required will be made and forwarded to [redacted] 25X1

7.3. Assistance will be required from TSSG/SSD for preparing the equipment site and for initial installation of the equipment.

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